



# DISCO CORPORATION

This is a multi-site certificate, additional site(s) are listed on the next page(s)

13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-8580, Japan

*Bureau Veritas Certification Holding SAS -UK Branch certifies that the Management System of the above organisation has been audited and found to be in accordance with the requirements of the management system standards detailed below*

## ISO9001:2015, JIS Q 9001:2015

### Scope of certification

- Design / development, manufacturing, installation / maintenance services and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of abrasive cut-off wheels.
- Supply of precision processing services.
- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Original cycle start date: **11 AUGUST 1995**

Expiry date of previous cycle: **N/A**

Recertification Audit date: **05 JULY 2024**

Recertification cycle start date: **05 AUGUST 2024**

Subject to the continued satisfactory operation of the organisation's Management System, this certificate expires on: **10 AUGUST 2027**

Certificate No. **22082636**

Version: **1.0**

Revision date: **05 AUGUST 2024**



0008

Certification body address: **5th Floor, 66 Prescot Street, London, E1 8HG, United Kingdom**

Local office: Bureau Veritas Japan Co., Ltd. Certification Division

**KRC bldg. 8F, 18, Nihon-odori, Naka-ku, Yokohama, 231-0021, Japan**

Further clarifications regarding the scope of this certificate and the applicability of the management system requirements may be obtained by consulting the organisation.

To check this certificate validity please call: **+81 (0)45-651-4784**





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## ISO9001:2015, JIS Q 9001:2015

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- Design / development and manufacturing of abrasive cut-off wheels.
- Supply of precision processing services.
- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
DISCO Corporation Head Office	13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-8580, Japan	<ul style="list-style-type: none"> <li>• Design / development and sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Design / development and sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Design / development and sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Supply of precision processing services.</li> </ul>
Kure Plant	1-23, Hiro Bunka-cho, Kure-shi, Hiroshima, 737-0198, Japan	<ul style="list-style-type: none"> <li>• Manufacturing and sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Design / development, manufacturing and sales of abrasive cut-off wheels.</li> </ul>

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- Supply of precision processing services.
- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
Kuwabata Plant	4010-1, Gohara-cho, Kure-shi, Hiroshima, 737-0161, Japan	<ul style="list-style-type: none"> <li>• Design / development and manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Design / development and manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Manufacturing of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> </ul>
Chino Plant	480, Toyohira, Chino-shi, Nagano, 391-0297, Japan	<ul style="list-style-type: none"> <li>• Design / development and manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> </ul>

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- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
Osaka Branch Office	3-16, Senba-higashi 3-chome, Minoh-shi, Osaka, 562-0035, Japan	<ul style="list-style-type: none"> <li>• Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of abrasive cut-off wheels.</li> </ul>
Kyushu Branch Office	2170-4, Tabaru, Mashiki-machi, Kamimashiki-gun, Kumamoto, 861-2202, Japan	<ul style="list-style-type: none"> <li>• Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> </ul>

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- Supply of precision processing services.
- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
Sendai Branch Office	5-1, Honcho 2-chome, Aoba-ku, Sendai-shi, Miyagi, 980-0014, Japan	<ul style="list-style-type: none"> <li>• Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> </ul>
DISCO HI-TEC TAIWAN CO., LTD.	1F, 9F., No.188, Baoqiao Rd., Xindian Dist., New Taipei City, Taiwan (R.O.C.)	<ul style="list-style-type: none"> <li>• Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> </ul>

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- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
DISCO HI-TEC AMERICA, INC.	5921 Optical Ct., San Jose, CA 95138, U.S.A.	<ul style="list-style-type: none"> <li>• Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Supply of precision processing services.</li> </ul>
DISCO HI-TEC (SINGAPORE) PTE LTD	80 Ubi Avenue 4, #06-01 Singapore 408831	<ul style="list-style-type: none"> <li>• Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> </ul>

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- Supply of precision processing services.
- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
DISCO HI-TEC EUROPE GmbH	Liebigstrasse 8, D-85551 Kirchheim b. Muenchen, Germany	<ul style="list-style-type: none"> <li>• Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Supply of precision processing services.</li> </ul>
DISCO HI-TEC KOREA Corporation	3F, DHK Solution Bldg., 28, Pangyo-ro 255beon-gil, Bundang-gu, Seongnam-si, Gyeonggi-do, Korea 13486	<ul style="list-style-type: none"> <li>• Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.</li> <li>• Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.</li> </ul>

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- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
DISCO KKM FACTORIES, LTD.	13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-0016, Japan	Supply of on-site electronics processing services.
DAIICHI COMPONENTS, LTD. HEAD OFFICE	13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-0016, Japan	Sales of various types of power sources, power generators, and motors.
DAIICHI COMPONENTS, LTD. CHINO PLANT	480, Toyohira, Chino-shi, Nagano, 391-0294, Japan	Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.
DISCO Manufacturing Corporation Hiroshima Works	2507-913, Gohara-cho, Kure-shi, Hiroshima, 737-0161, Japan	Manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.

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